

wherein the step of forming the build-up wiring layer is adapted so that a first wiring layer is formed via a step of forming photosensitive dielectric layer onto the entire surface of the build-up formation surface of the base substrate portion, a via formation step and a step of forming a conductive pattern or patterns onto the photosensitive dielectric layer, and wiring layers of upper layers are formed in succession via similar steps onto the first wiring layer, and a step of forming solder resist layer and an electrode formation step are implemented to the wiring layer of the uppermost layer to mount high frequency circuit components (parts).

Respectfully submitted,

(Reg. #37,607)

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